

# Wi-Fi®/ Bluetooth® Modules

## Wi-Fi® modules

### Type 1FX

PN: LBWA1KL1FX-875

CYW43364 Chipset

6.95 x 5.15 x 1.1mm

FCC/IC/CE\*/Japan Certified



## Wi-Fi® + Bluetooth® modules



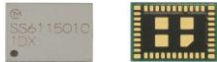
### Type 1DX

PN: LBEE5KL1DX-883

CYW4343W Chipset

6.95 x 5.15 x 1.1 mm

FCC/IC/CE\*/Japan Certified



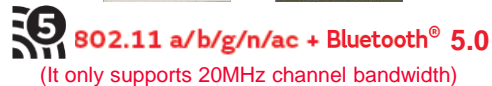
### Type 1LV

PN: LBEE59B1LV-278

CYW43012 Chipset

10.0 x 7.2 x 1.4 mm

FCC/IC/CE\*/Japan Certified



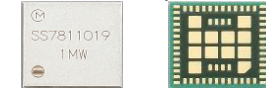
### Type 1MW

PN: LBEE5HY1MW-230

CYW43455 Chipset

7.9 x 7.3 x 1.1 mm

FCC/IC/CE\*/Japan Certified



### Type 1CX

PN: LBEH5UL1CX-887

CYW4356 Chipset

11.5 x 8.8 x 1.0 mm



MIMO



### Type 1VA

PN: LBEE5XV1VA-495

CYW88359 Chipset

11.4 x 8.9 x 1.4 mm

FCC/IC/CE\*/Japan Certified



MIMO  
RSDB

\*Conducted results for CE Marking Conformity Assessment Procedures are available

# Wi-Fi® MCU Modules

## ElectricImp modules


electric imp

 **Type 1GC/Imp005**  
PN: LBWA1UZ1GC-958  
PN: LBWA1UZ1GC-901 (Imp005)  
CYW43907 Chipset  
10.0 x 10.0 x 1.3 mm



WICED, ElectricImp  
FCC/IC/CE\* Reference Certified


 **802.11 a/b/g/n**  
+ Ethernet + ARM Cortex-R4

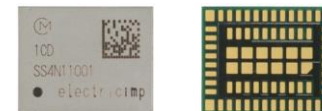
 **Type 1MD/Imp004m**  
PN: LBEE5ZZ1MD-011  
CYW43438+STM Chipset  
21.0 x 17.5 x 2.3 mm



ElectricImp  
FCC/IC/CE\*/Japan Certified

 **802.11 b/g/n + Bluetooth® 4.1**  
+ ARM Cortex-M4


 **Type 1CD/Imp003**  
PN: LBWA1ZV1CD-716  
CYW43362+STM Chipset  
10.0 x 7.9 x 1.25 mm

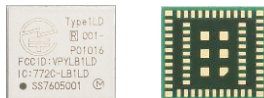


ElectricImp  
FCC/IC/CE\* Reference Certified

 **802.11 b/g/n**  
+ ARM Cortex-M4


## Ayla modules

 **Type 1LD**  
PN: LBEE5PA1LD-005  
PN: LBEE5PA1LD-222 (Ayla)  
CYW43438+STM Chipset  
8.9 x 7.8 x 1.2 mm



WICED, Ayla  
FCC/IC/CE\*/Japan Certified

 **802.11 b/g/n + Bluetooth® 4.2**  
+ ARM Cortex-M4

 **Type 1AD**  
PN: LBWA1CS1AD-806  
CYW4390 Chipset  
9.4 x 8.9 x 1.2 mm



Ayla  
FCC/IC/CE\* Reference Certified

 **802.11 b/g/n + ARM Cortex-M3**



## Wi-Fi MCU modules

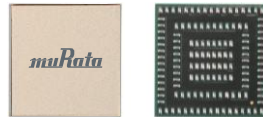


### Type 1PS

PN: LBWA1UZ1PS-241

CYW54907 Chipset

10.0 x 10.0 x 1.3 mm



WICED

FCC/IC/CE\*/Japan Certified



802.11 a/b/g/n/ac + Bluetooth®



## Wi-Fi/BT MCU modules

### Type 1QP

PN: LBEE5WQ1QP-276

CYW43907+CYW20707 Chipset

11.0 x 11.0 x 1.2 mm



WICED



802.11 a/b/g/n + Bluetooth® 5.0  
+ ARM Cortex- R4

### Type 1QX

PN: LBEE5WQ1QX-277

CYW54907+CYW20707 Chipset

11.0 x 11.0 x 1.2 mm



WICED



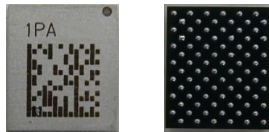
802.11 a/b/g/n + Bluetooth® 5.0  
+ ARM Cortex- R4

# Bluetooth®/ BLE Modules



## Type 1PA

PN: LBCA1KU1PA-245  
CYW20719 Chipset  
5.9 x 5.1 x 1.17mm

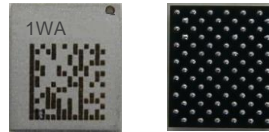


Bluetooth/BLE  
WICED Studio

**Bluetooth® 5.0**

## Type 1WA

PN: LBCA1KU1WA  
CYW20721 Chipset  
5.9 x 5.1 x 1.17mm



Bluetooth/BLE  
WICED Studio

**Bluetooth® 5.0**

## Type 1GR

PN: LBCA1ZZ1GR-084  
CYW20736 chipset  
9.0 x 7.0 x 1.2mm



BLE  
WICED Studio  
FCC/IC/CE\*/Japan Certified

**Bluetooth® 4.1**



\*Conducted results for CE Marking Conformity Assessment Procedures are available

# Wi-Fi®/ Bluetooth® Modules

## Wi-Fi® + Bluetooth® MCU modules

### Type 1KP/1KQ/1KR/1KS

PN: LBWA1ZZ1KP-289

PN: LBWA1ZZ1KQ-290

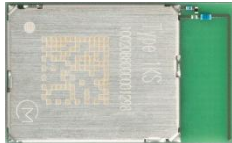
PN: LBWA1ZZ1KR-291

PN: LBWA1ZZ1KS-088

TI CC3120/CC3220

CC3220S/CC3220SF

13.2 x 21.45 x 2.65mm



SimpleLink Gen2 SDK

802.11 b/g/n

+ ARM Cortex-M3

FCC/IC/CE\*/Japan Certified

## Wi-Fi® + Bluetooth® modules

### Type WT

PN: LBEP5CLWTC-631

WL1801/1831 Chipset

9.9 x 8.8 x 1.3 mm

-40 ~ 75°C



802.11 b/g/n + Bluetooth® 4.2

### Type WM

PN: LBEP5CLWMC-633

WL1803/1833 Chipset

9.9 x 8.8 x 1.3 mm

-40 ~ 75°C



802.11 a/b/g/n + Bluetooth® 4.2

Japan Certified

### Type XR

PN: LBEP5CLXRC-701

WL1801 Chipset

9.9 x 8.8 x 1.3 mm

-40 ~ 85°C



802.11 b/g/n